

N-Channel Power MOSFET

650V, 2.0A, 5Ω

FEATURES

- 100% UIS & R_g tested
- Pb-free plating
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS

PARAMETER	VALUE	UNIT
V_{DS}	650	V
$R_{DS(on)}$ (max)	5	Ω
Q_g	13	nC

APPLICATION

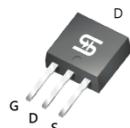
- Power Supply
- AC/DC LED Lighting



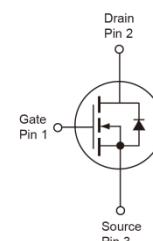
✓
ROHS
COMPLIANT

HALOGEN
FREE

TO-251 (IPAK SL)



TO-252 (DPAK)



Notes: MSL 3 (Moisture Sensitivity Level) for TO-252 (D-PAK) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	2.0	A
		1.4	
Pulsed Drain Current ^(Note 1)	I_{DM}	8.0	A
Total Power Dissipation @ $T_C = 25^\circ\text{C}$	P_{DTOT}	65	W
Single Pulsed Avalanche Energy ^(Note 2)	E_{AS}	25	mJ
Single Pulsed Avalanche Current ^(Note 2)	I_{AS}	1.6	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Case Thermal Resistance	$R_{\Theta JC}$	1.9	°C/W
Junction to Ambient Thermal Resistance	$R_{\Theta JA}$	62.5	°C/W

Notes: $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\Theta JA}$ is guaranteed by design while $R_{\Theta CA}$ is determined by the user's board design. $R_{\Theta JA}$ shown below for single device operation on FR-4 PCB in still air.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static ^(Note 3)						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$	BV_{DSS}	650	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	$V_{GS(\text{TH})}$	2	2.5	4	V
Gate Body Leakage	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 650\text{V}$, $V_{GS} = 0\text{V}$	I_{DSS}	--	--	10	μA
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}$, $I_D = 1\text{A}$	$R_{DS(\text{ON})}$	--	4	5	Ω
Forward Transfer Conductance	$V_{DS} = 10\text{V}$, $I_D = 1\text{A}$	g_{fs}	--	2.5	--	S
Dynamic ^(Note 4)						
Total Gate Charge	$V_{DS} = 520\text{V}$, $I_D = 2\text{A}$, $V_{GS} = 10\text{V}$	Q_g	--	13	--	nC
Gate-Source Charge		Q_{gs}	--	2.2	--	
Gate-Drain Charge		Q_{gd}	--	5	--	
Input Capacitance	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $F = 1.0\text{MHz}$	C_{iss}	--	390	--	pF
Output Capacitance		C_{oss}	--	31	--	
Reverse Transfer Capacitance		C_{rss}	--	8	--	
Gate Resistance	$f = 1.0\text{MHz}$, open drain	R_g	0.8	2.5	7.5	Ω
Switching ^(Note 5)						
Turn-On Delay Time	$V_{GS} = 10\text{V}$, $I_D = 2\text{A}$, $V_{DD} = 325\text{V}$, $R_G = 25\Omega$	$t_{d(on)}$	--	8.2	--	ns
Turn-On Rise Time		t_r	--	23.2	--	
Turn-Off Delay Time		$t_{d(off)}$	--	38	--	
Turn-Off Fall Time		t_f	--	27	--	
Source-Drain Diode ^(Note 3)						
Diode Forward Voltage	$I_S = 2\text{A}$, $V_{GS} = 0\text{V}$	V_{SD}	--	--	1.2	V

Notes:

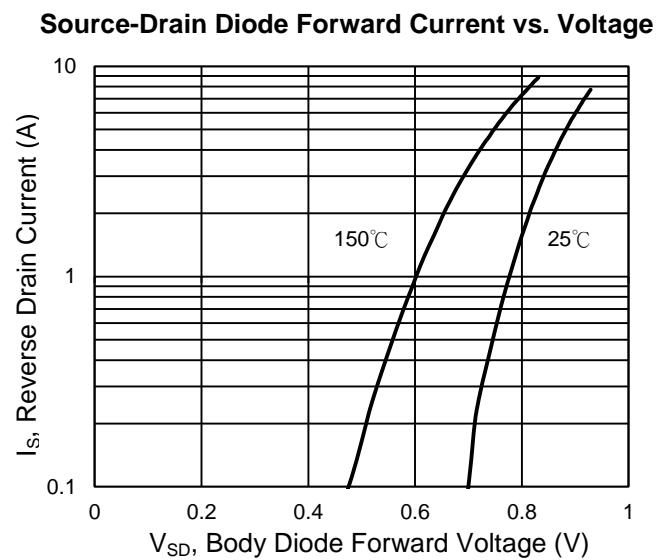
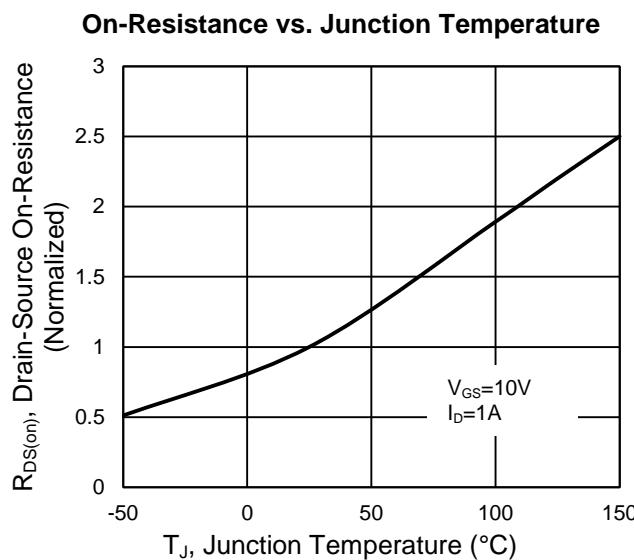
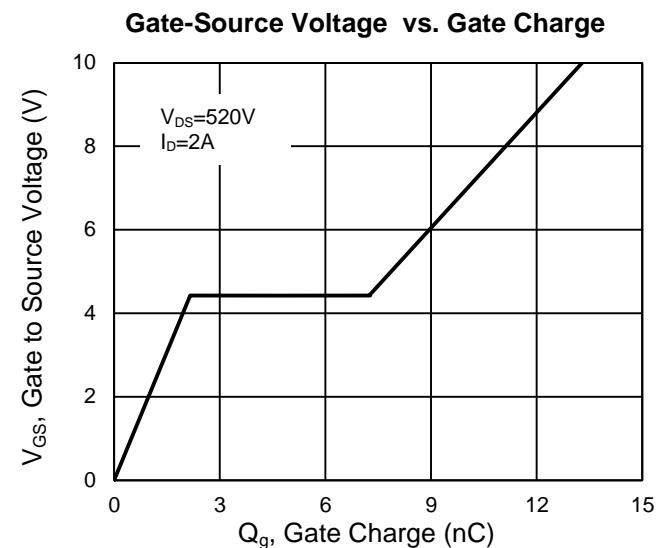
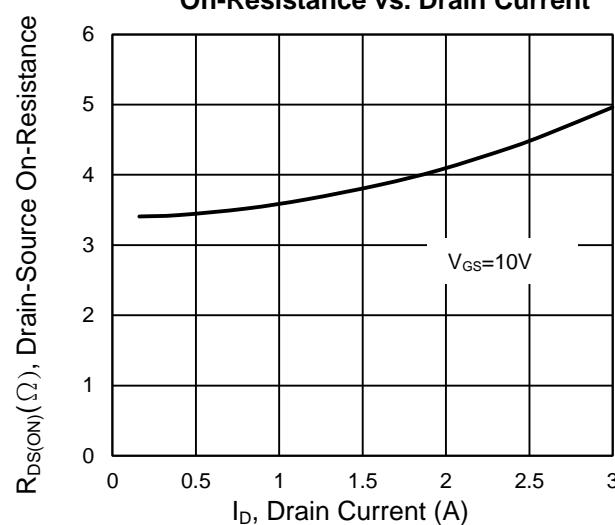
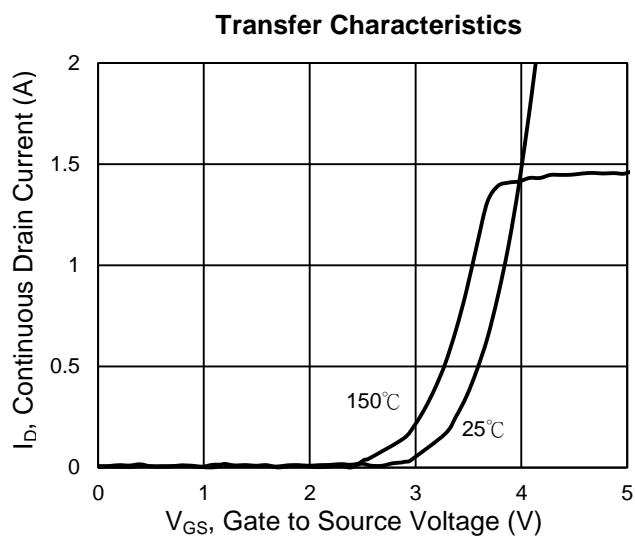
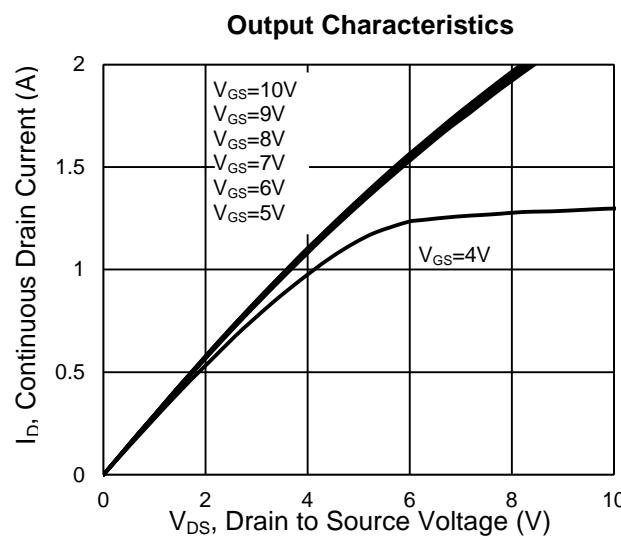
1. Pulse width limited by the maximum junction temperature
2. $L = 20\text{mH}$, $I_{AS} = 1.6\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. Pulse test: PW $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
4. For DESIGN AID ONLY, not subject to production testing.
5. Essentially Independent of Operating Temperature.

ORDERING INFORMATION

PART NO.	PACKAGE	PACKING
TSM2NB65CH X0G	TO-251S	75pcs / Tube
TSM2NB65CP ROG	TO-252	2,500pcs / 13" Reel

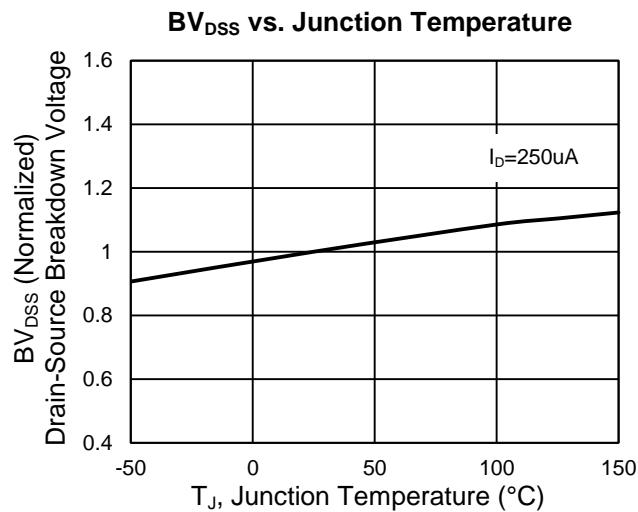
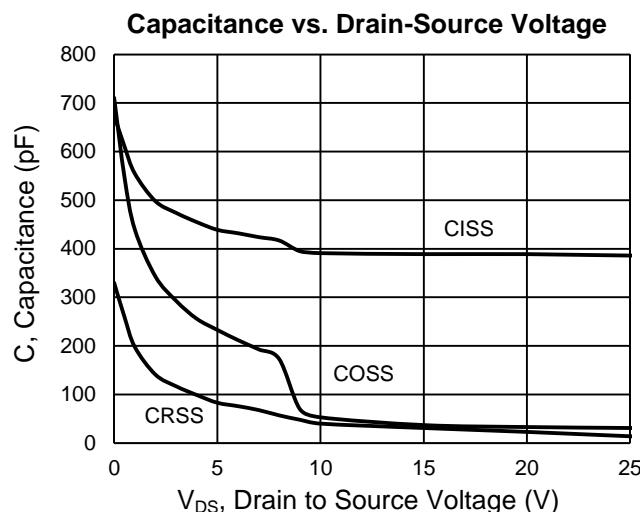
CHARACTERISTICS CURVES

($T_C = 25^\circ\text{C}$ unless otherwise noted)

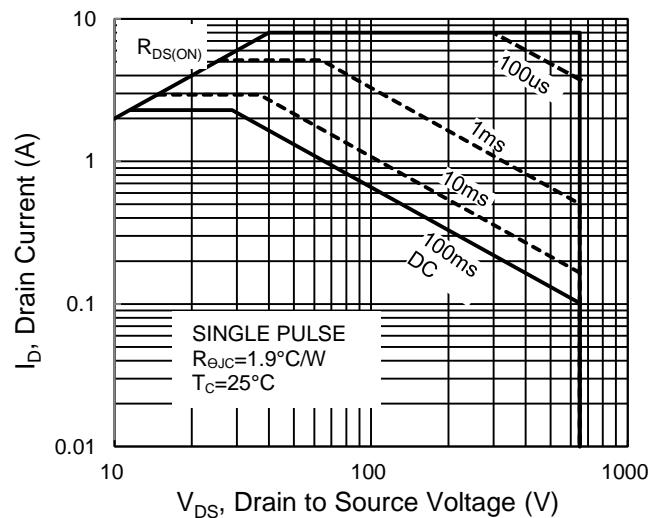


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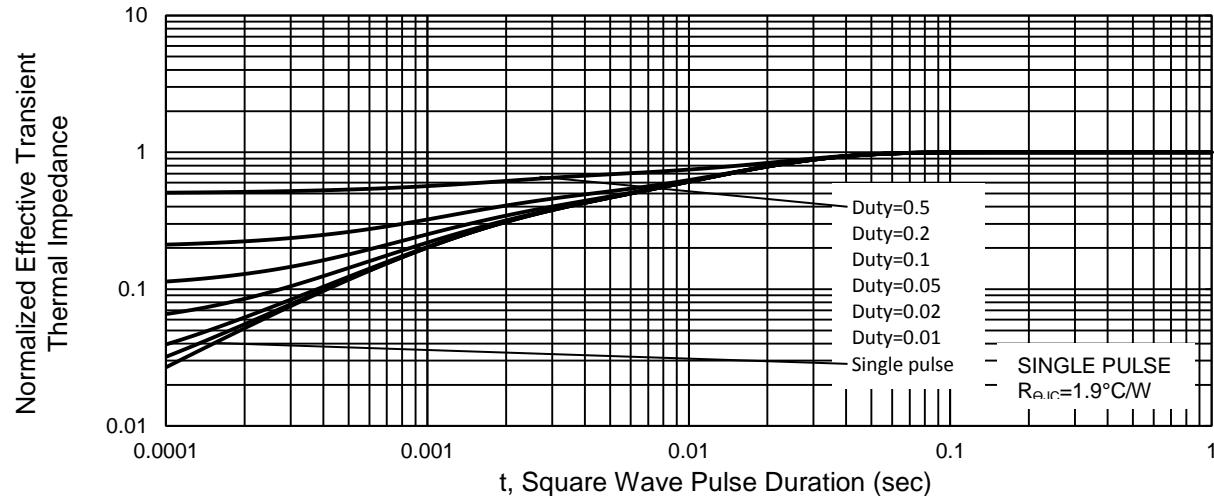
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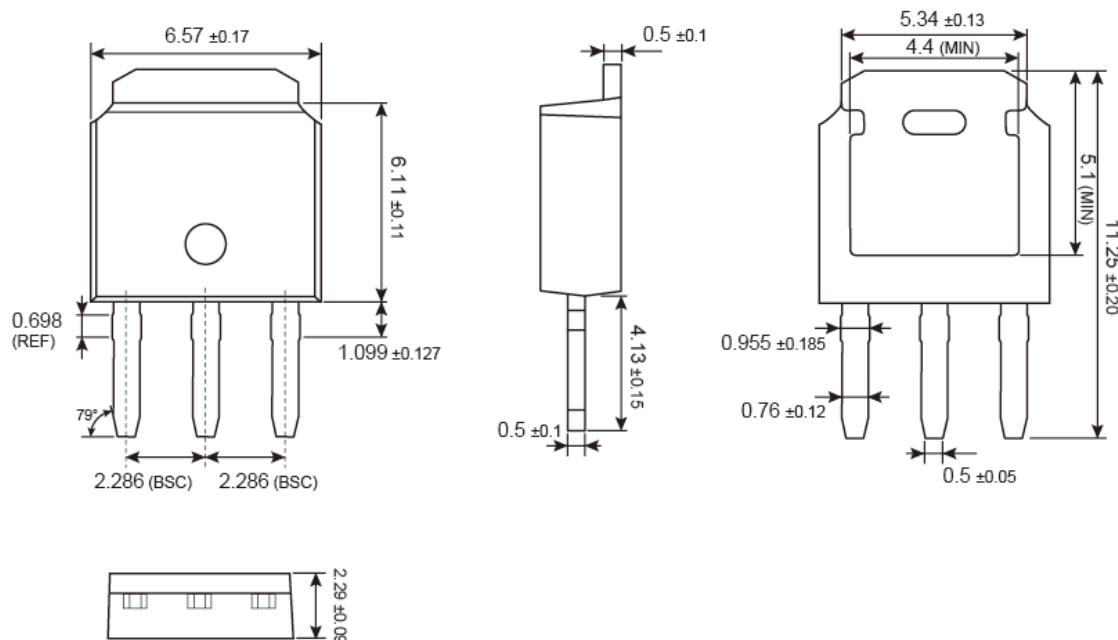
Maximum Safe Operating Area (TO-251/252)



Normalized Thermal Transient Impedance, Junction-to-Case (TO-251/252)



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-251S

MARKING DIAGRAM

Y = Year Code

M = Month Code for Halogen Free Product

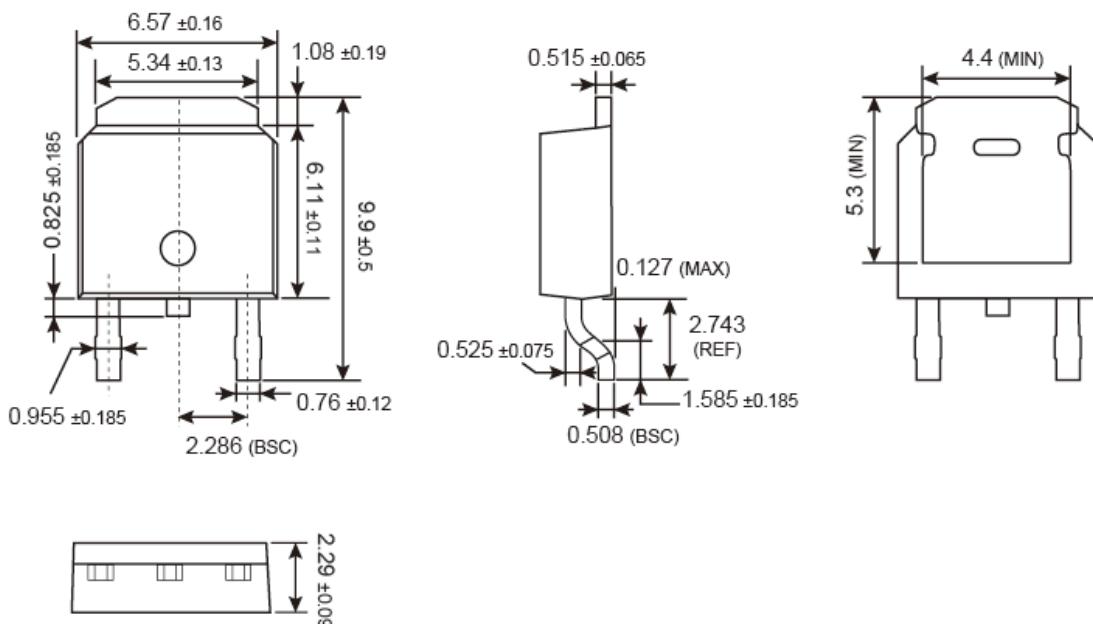
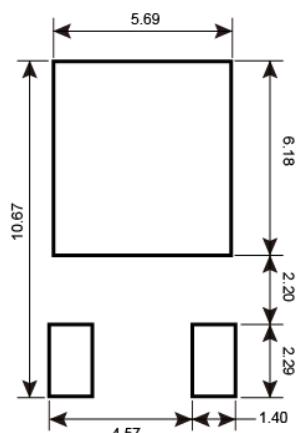
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W =Sep **X** =Oct **Y** =Nov **Z** =Dec

L = Lot Code (1~9, A~Z)

PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-252

SUGGESTED PAD LAYOUT (Unit: Millimeters)

MARKING DIAGRAM

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